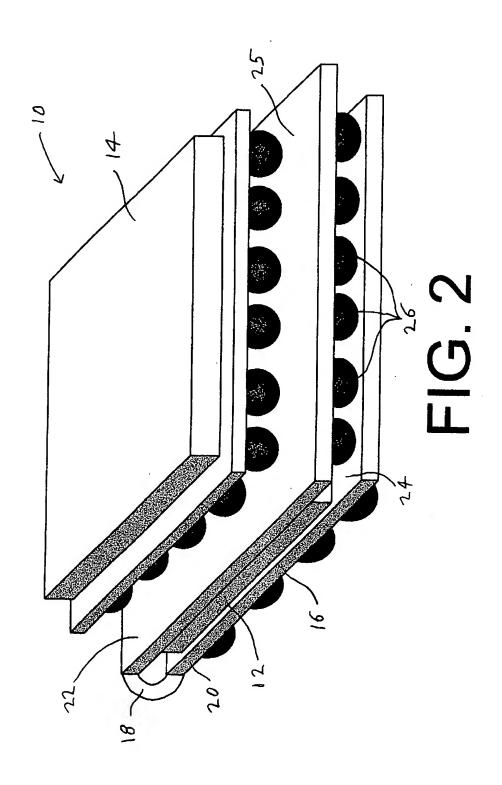
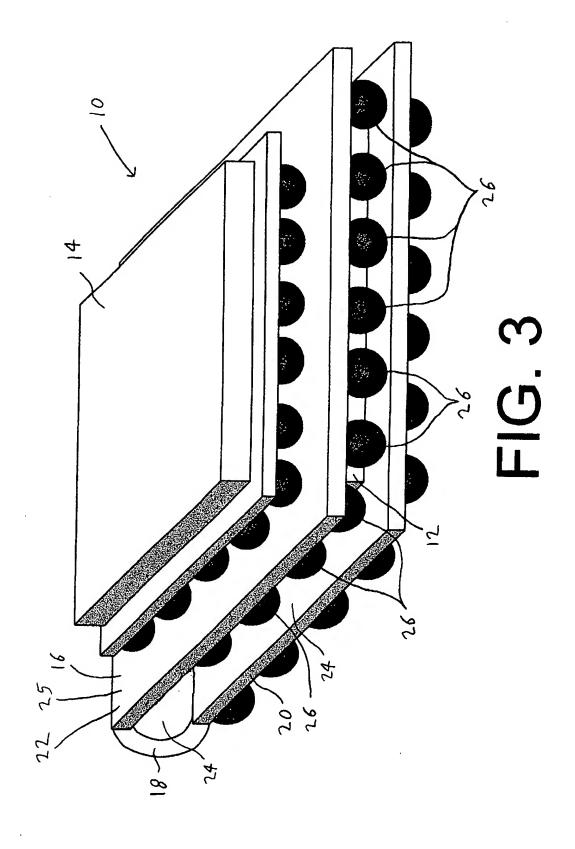
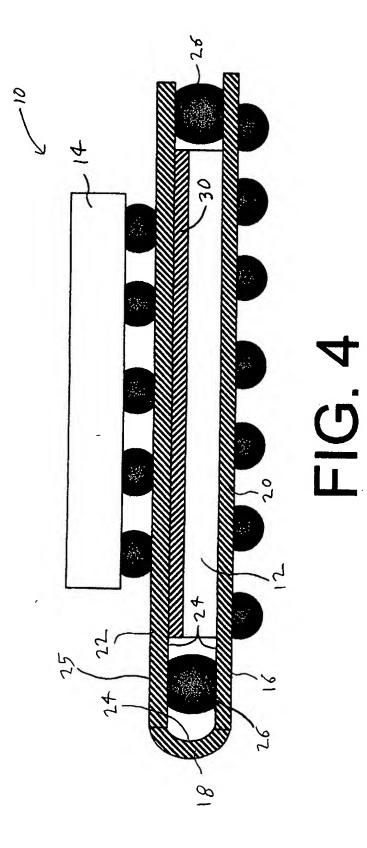


FIG. 1







52

securing a first die to a first section of an interposer, the interposer including a first conductor and a second conductor on a first surface of the interposer

- soldering the first die to the interposer

-54

folding the interposer to secure the first die to a second section of the interposer and to connect the first conductor to the second conductor to form a contact

- soldering the first conductor to the second conductor
- placing an adhesive on the first die and connecting the second section of the interposer to the adhesive
- forming a contact on an opposing side of the first die
- connecting each of the conductors to another conductor to form a plurality of contacts that extend from the first surface of the interposer between the first section and the second section
  - forming at least one contact on an opposing side of the first die
  - forming at least one contact on each side of the first die except for the one side of the first die
  - forming at least one contact on each side of the first die

. 56

securing a second die to a second surface of the interposer such that the first and second dice are stacked one on top of another and electrically coupled by the interposer and the contact

soldering the second die to the second surface of the interposer

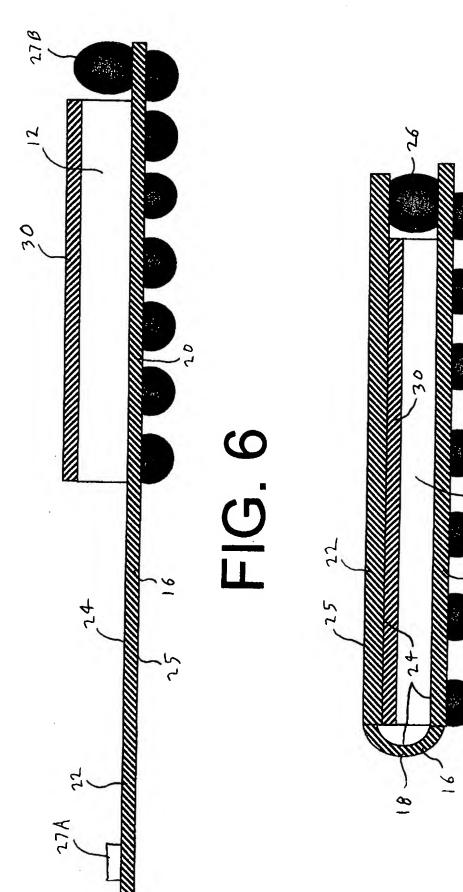


FIG. 7

